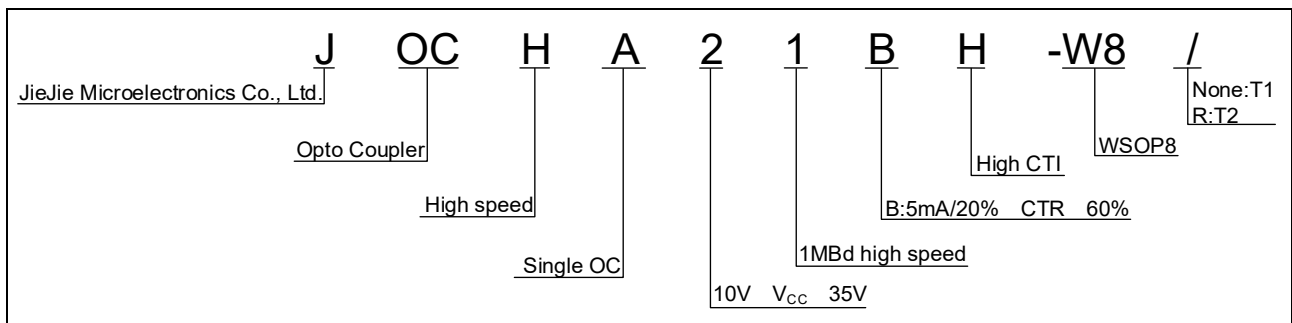




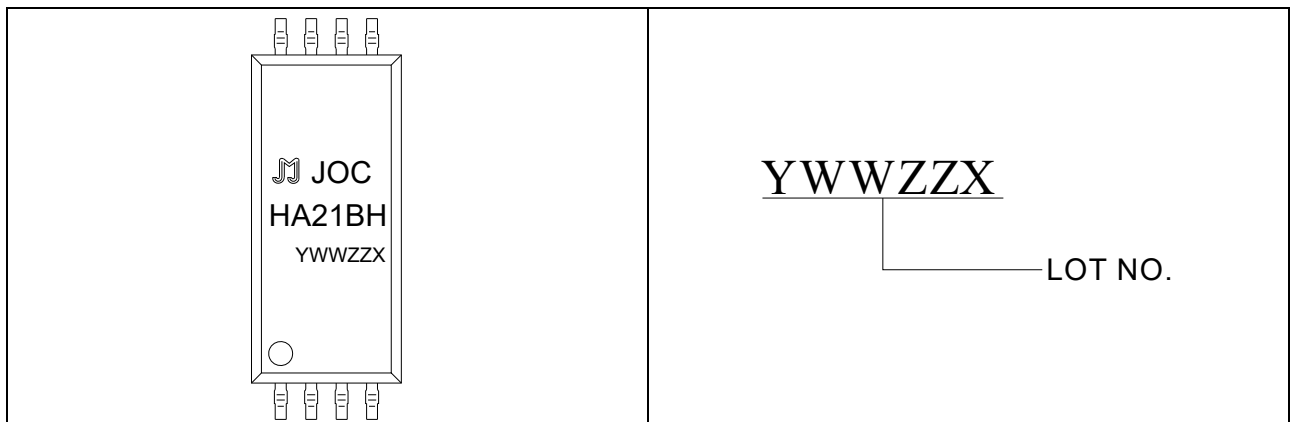
	Output Current	$I_o$	8	mA
	Output Power Dissipation	$P_o$	100	mW
Total Power Dissipation		$P_{tot}$	200	mW
Isolation Voltage		$V_{iso}$	7500	Vrms
Operating Temperature		$T_{opr}$	-55~110	
Junction Temperature		$T_j$	125	
Storage Temperature		$T_{stg}$	-55~125	
Soldering Temperature		$T_{sol}$	260	

100 $\mu$ s pulse, 100Hz frequency  
 AC for 1minute, R.H.=40~60%

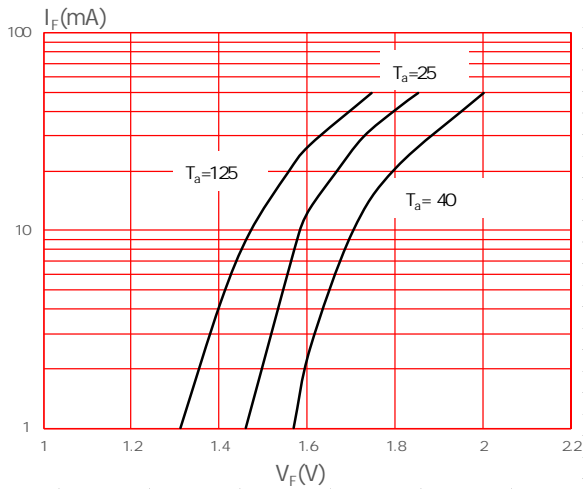
			$V_{CC}=5V$				
Common Mode Transient Immunity at Logic High	CM <sub>H</sub>	$I_F=0mA,$ $V_{CM}=400V_{pp},$ $R_L=4.1k\Omega$	15	20	-	kV/ $\mu s$	
Common Mode Transient Immunity at Logic Low	CM <sub>L</sub>	$I_F=16mA,$ $V_{CM}=400V_{pp},$ $R_L=4.1k\Omega$	-15	-20	-	kV/ $\mu s$	



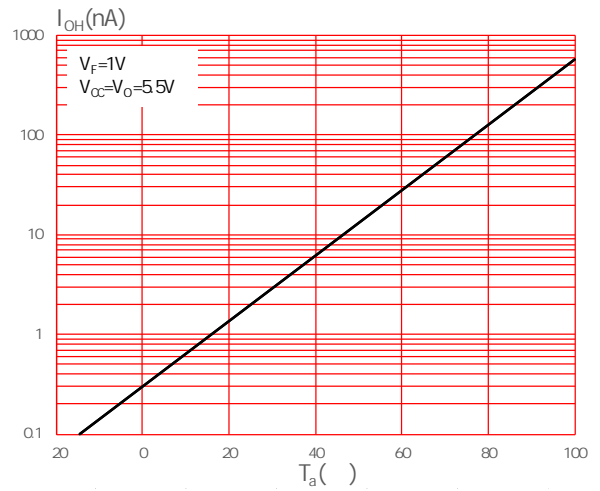
None/R	1200 Units/Reel



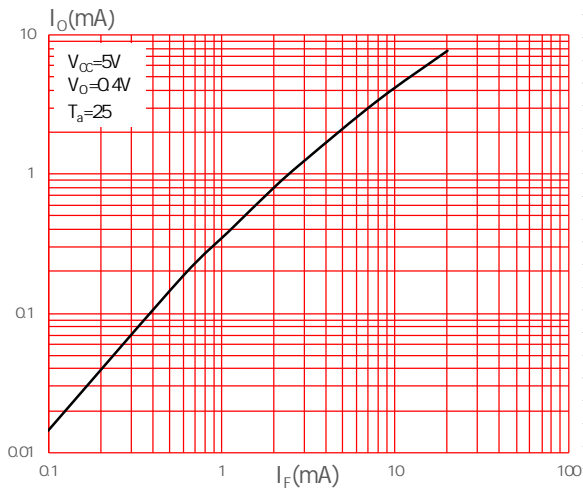
**FIG.1:** Forward Current vs. Forward Voltage



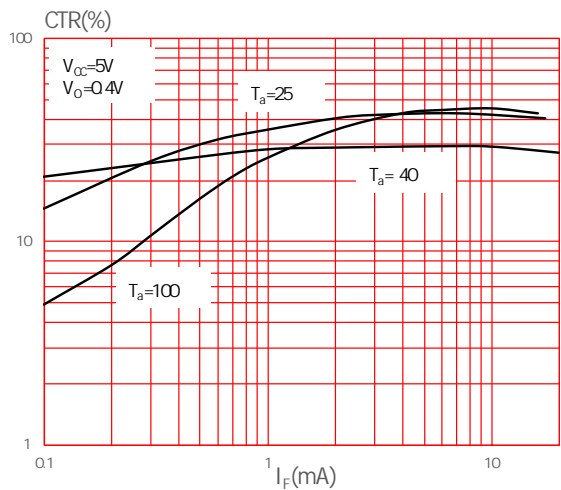
**FIG.2:** High Level Output Current vs. Ambient Temperature



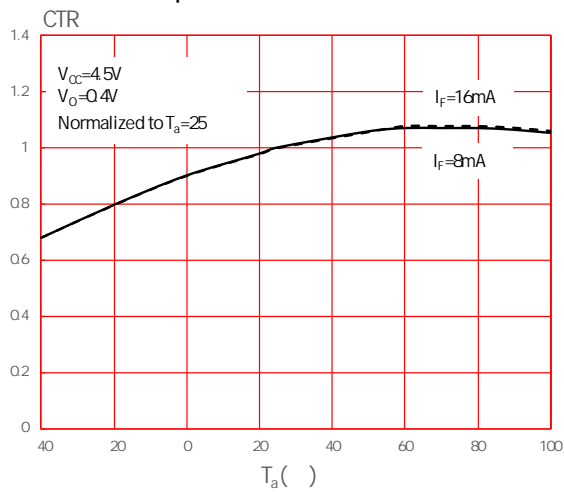
**FIG.3:** Output Current vs. Forward Current



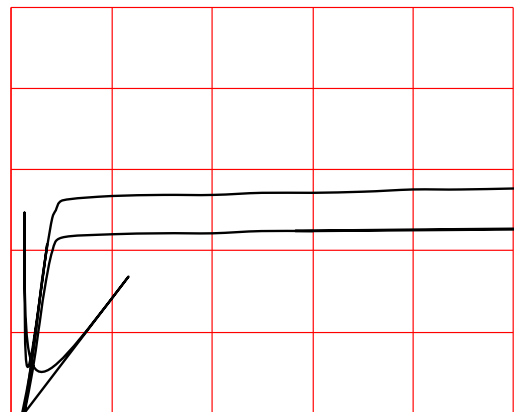
**FIG.4:** Current Transfer Ratio vs. Forward Current



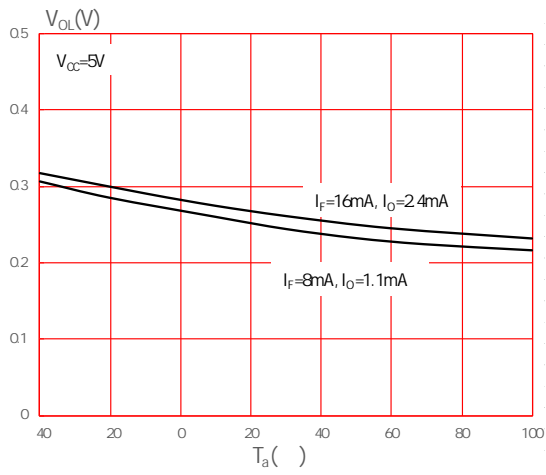
**FIG.5:** Normalized Current Transfer Ratio vs. Ambient Temperature



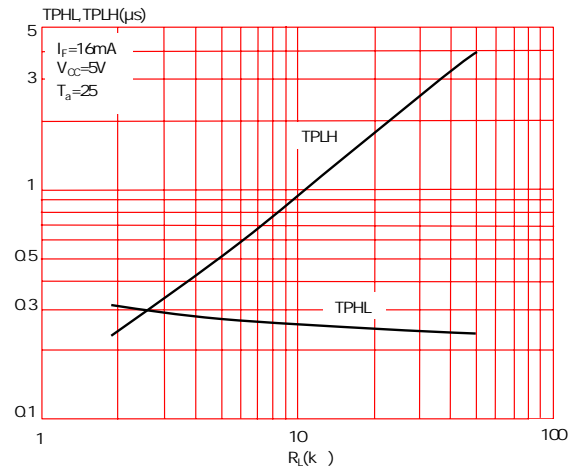
**FIG.6:** Output Current vs. Output Voltage



**FIG.7:** Low Level Output Voltage vs. Ambient Temperature



**FIG.8:** Propagation Delay vs. Load Resistance



**FIG.9:** Propagation Delay vs. Ambient Temperature

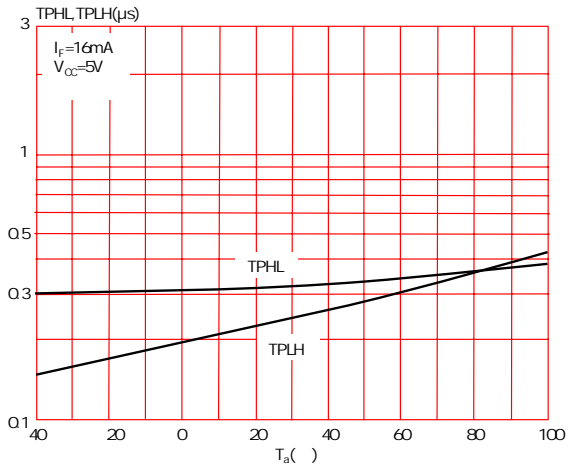


Fig.10: Test Circuit of tPHL, tPLH

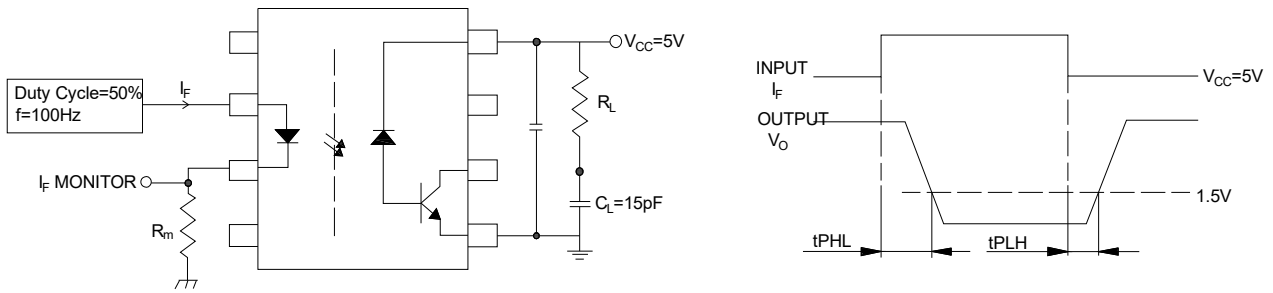
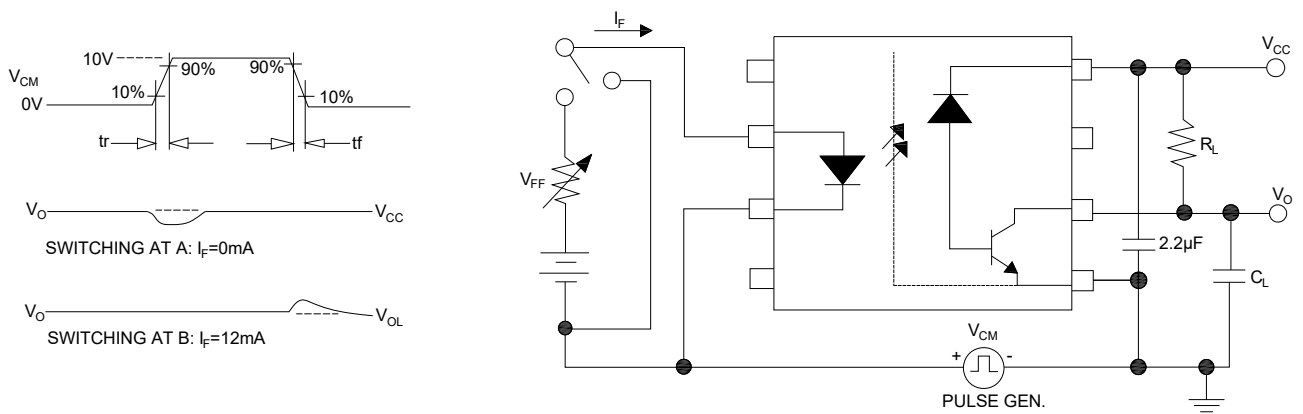
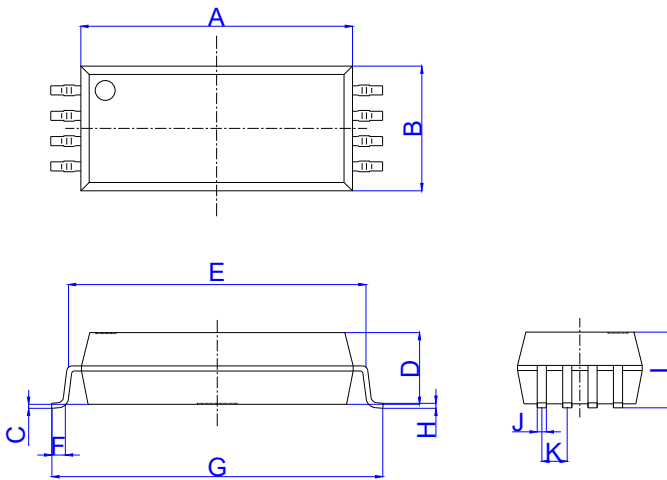
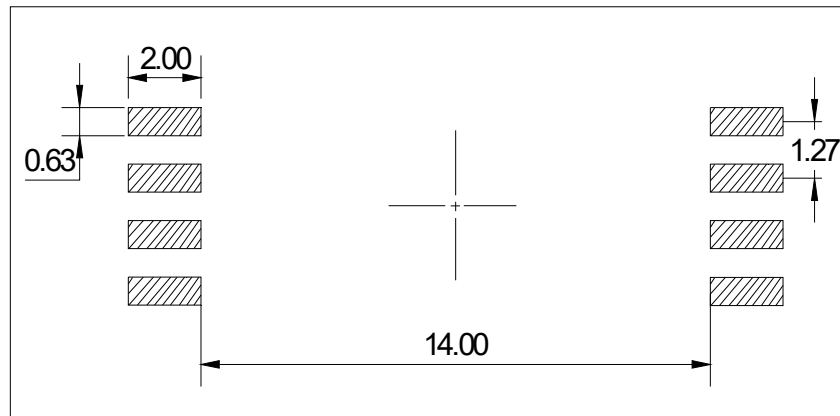


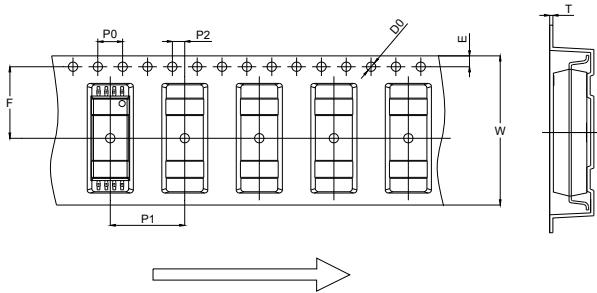
Fig.11: Test Circuit for Transient Immunity and Typical Waveforms



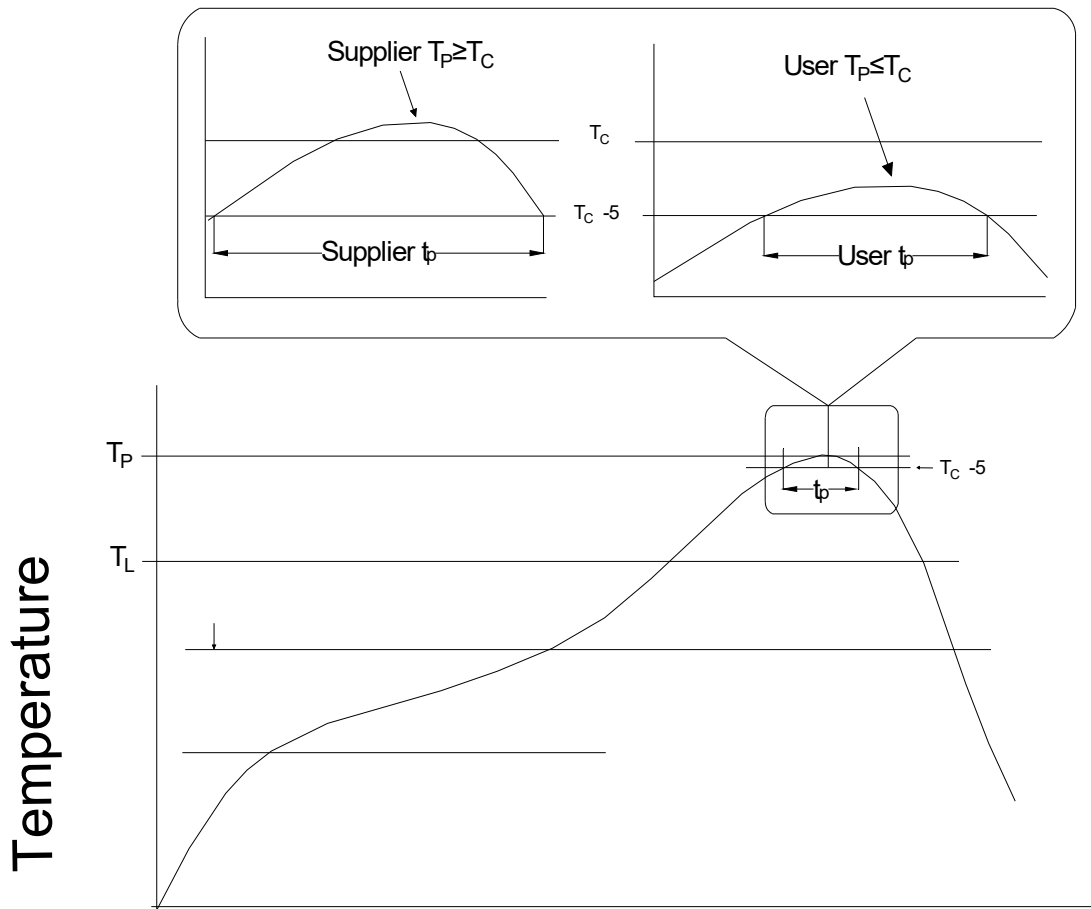


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	13.50		13.70	0.531		0.539
B	6.15		6.35	0.242		0.250
C	0.10		0.30	0.004		0.012
D	3.50		3.70	0.138		0.146
E	14.71		15.31	0.579		0.603
F	0.52		1.02	0.020		0.040
G	16.36		16.86	0.644		0.664
H	0.10		0.40	0.004		0.016
I	3.65		3.95	0.144		0.156
J	0.307		0.607	0.012		0.024
K	1.02		1.52	0.040		0.060





Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	11.40	11.50	11.60	0.449	0.453	0.457
T	0.35	0.40	0.45	0.014	0.016	0.018
W	23.70	24.00	24.30	0.933	0.945	0.957




Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage humidity: <60%;  
MSL level: MSL 1

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